



Material Content Data Sheet



Sales Product Name		TLE75080-ESD		Issued		1. August 2018		
MA#		MA001709732						
Package		PG-TSDSO-24-21		Weight*		796.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	0.39	0.39	3883	3883
leadframe	inorganic material	phosphorus	7723-14-0	0.064	0.01		80	
	non noble metal	zinc	7440-66-6	0.256	0.03		321	
	non noble metal	iron	7439-89-6	5.116	0.64		6422	
wire	non noble metal	copper	7440-50-8	207.751	26.07	26.75	260748	267571
	non noble metal	copper	7440-50-8	0.764	0.10	0.10	958	958
	encapsulation	organic material	carbon black	1333-86-4	1.724	0.22		2164
encapsulation	plastics	epoxy resin	-	67.233	8.44		84383	
	inorganic material	silicondioxide	60676-86-0	505.681	63.47	72.13	634678	721225
leadfinish	non noble metal	tin	7440-31-5	3.642	0.46	0.46	4571	4571
plating	noble metal	silver	7440-22-4	0.339	0.04	0.04	426	426
glue	plastics	epoxy resin	-	0.190	0.02		239	
	noble metal	silver	7440-22-4	0.898	0.11	0.13	1127	1366
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com